

# Introduction to ATmega328P MCU

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# Introduction to AVR microcontrollers

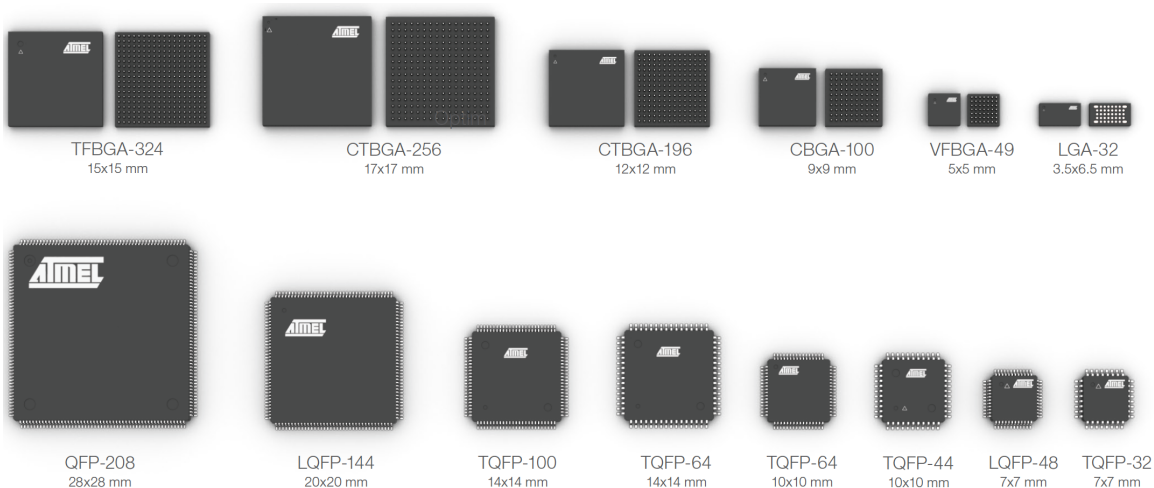
- Initially designed by two students at the Norwegian Institute of Technology
- AVR was developed in the year 1996 by Atmel Corporation<sup>1</sup>
- Available in three categories<sup>2</sup>:
  - TinyAVR—General purpose microcontrollers with up to 16K Bytes Flash program memory, 512 Bytes SRAM and EEPROM.
  - MegaAVR —High performance microcontrollers with Hardware Multiplier. Up to 256KB Flash, 4K Bytes EEPROM and 8KB SRAM.
  - XmegaAVR —Advanced peripherals, high, performance, DMA and Event system
  - AVR32 UC3—High performance, low power 32-bit AVR32 flash microcontrollers. Up to 512 KBytes Flash, 128 KB SRAM.
  - AVR32 AP7—High performance, low power, 32-bit CPU, and up to 32KB SRAM.
- AVR are faster, consume less power compared to some other 8-bit MCU such as PIC and intel 8051

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<sup>1</sup>[https://en.wikipedia.org/wiki/AVR\\_microcontrollers](https://en.wikipedia.org/wiki/AVR_microcontrollers)

<sup>2</sup><https://www.engineersgarage.com/avr-microcontroller-all-you-need-to-know-part-1-46/>

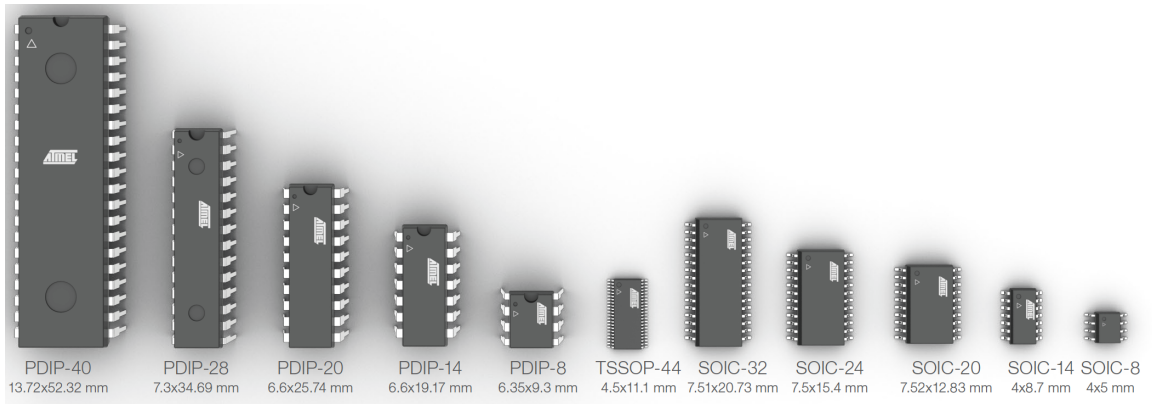
# AVR MCU Packaging<sup>3</sup>



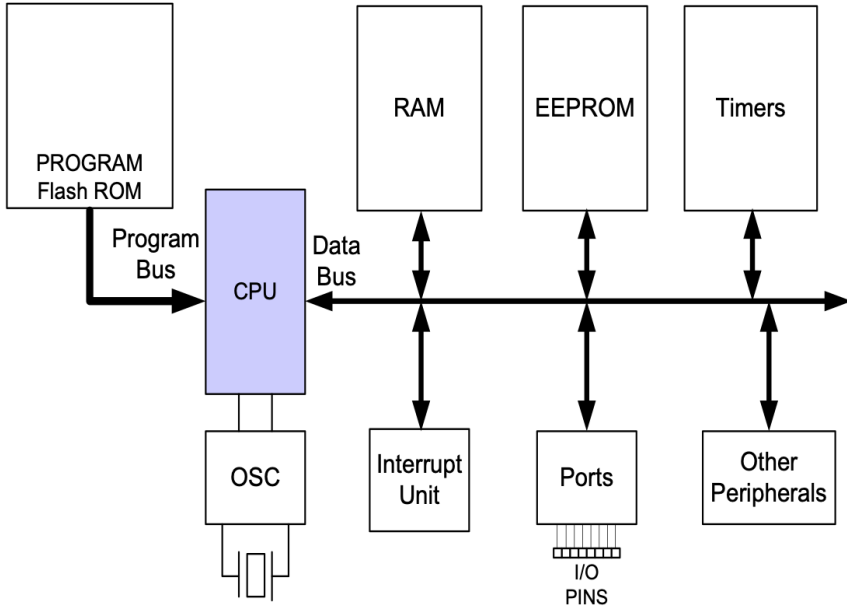
**FIG 1.** Surface Mount Packages

<sup>3</sup><https://www.engineersgarage.com/ic-packages-types/>

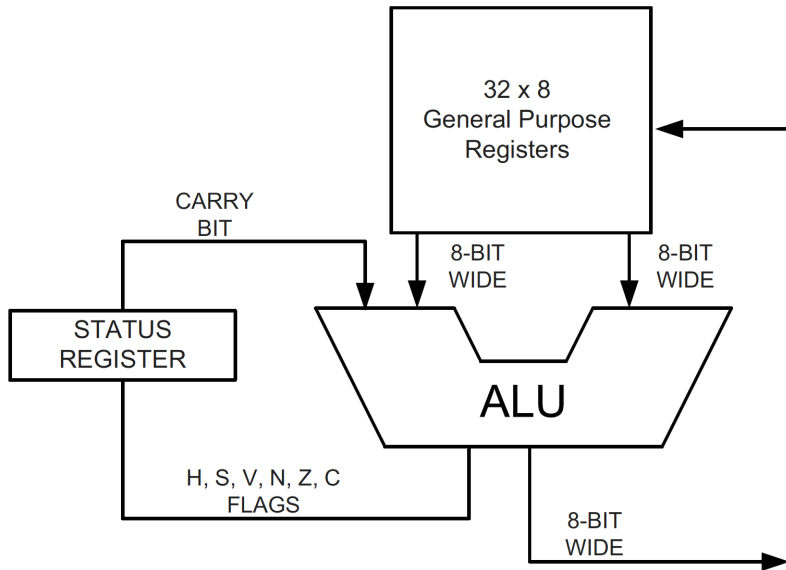
# AVR MCU Packaging



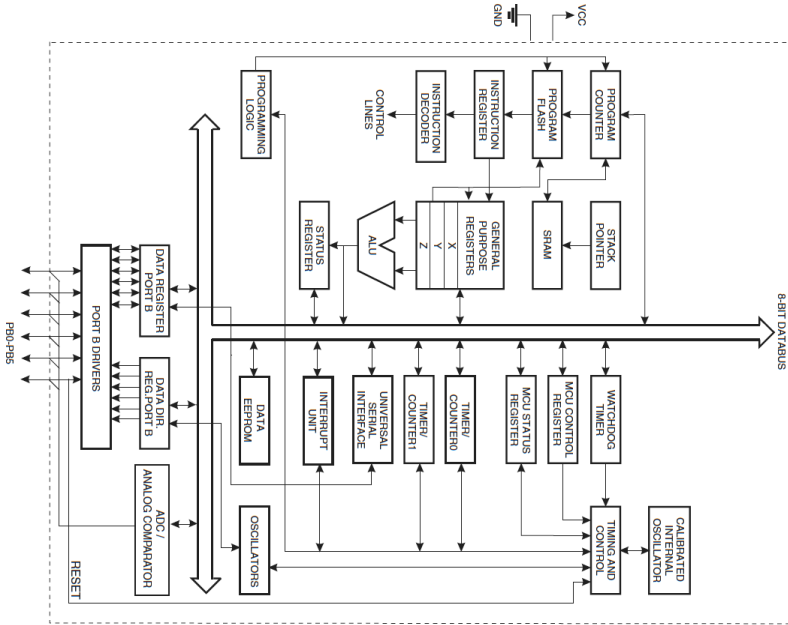
**FIG 2.** Dual In-line Packages



**FIG 3.** Simplified View of an AVR Microcontroller



**FIG 4.** AVR General Purpose Registers and ALU

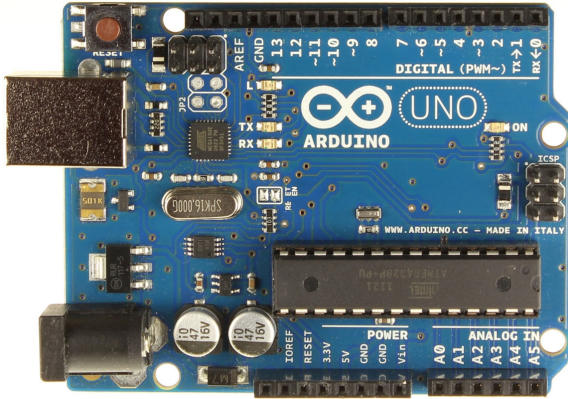


**FIG 5. ATtiny25 Block Diagram**

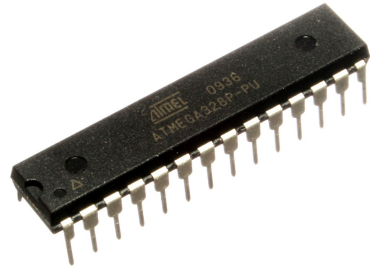
# Introduction to the ATmega328



# It's the MCU in the Arduino UNO



**FIG 6.** Arduino Uno SMD R3



**FIG 7.** ATmega328P in dual in-line package

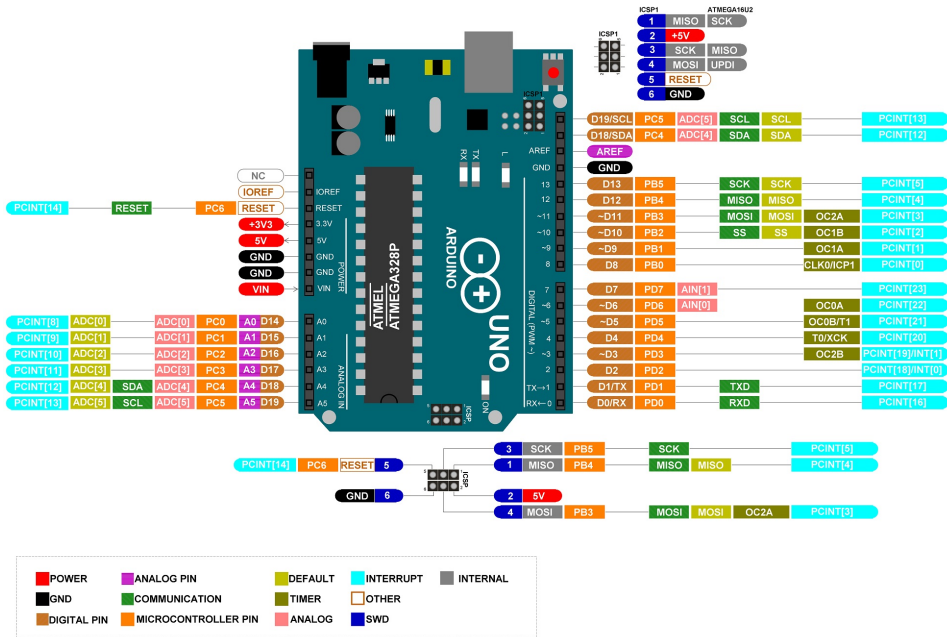
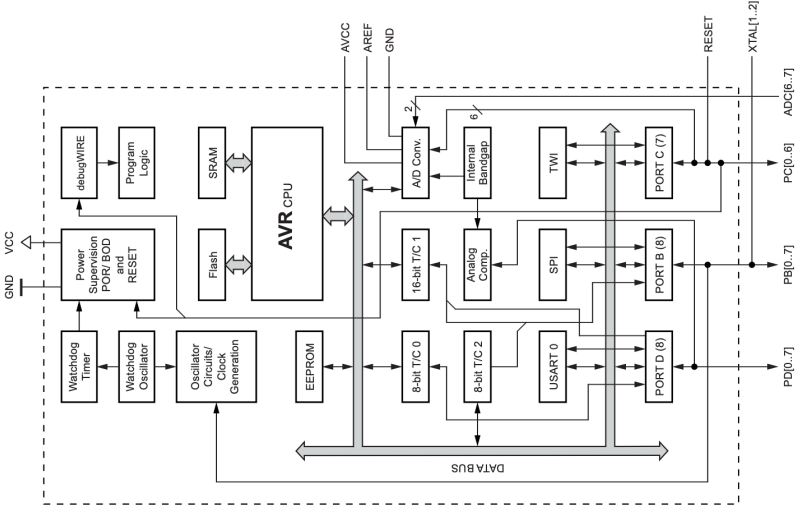


FIG 8. ATmega328P-Arduino Pin Mapping

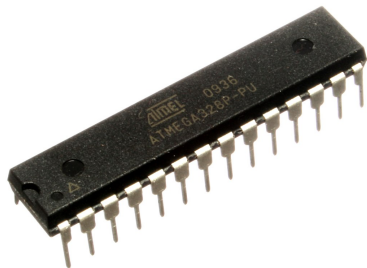
# Atmega 328 architecture



**FIG 9.** Atmega328 block diagram

# Atmega 328 architecture

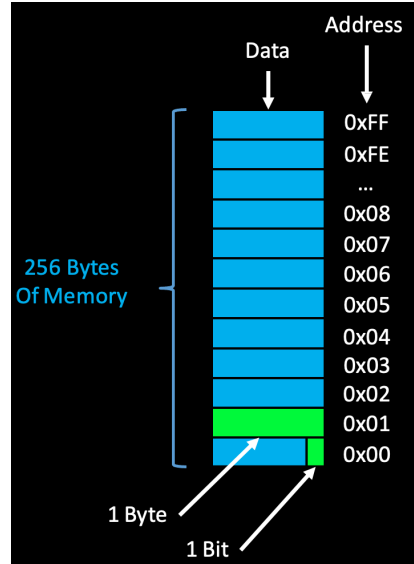
- Harvard architecture
- Programmable memory: 32K flash
- Data memory 2K SRAM
- Long term memory EEPROM: 1K
- Maximum CPU speed: 20 MHz
- 32 8-bit general purpose registers in SRAM memory space
- 3 8-bit Ports (B, C, D)—Each port controlled by 3 8-bit registers
- Digital Communication Peripherals: 1-UART, 2-SPI, 1-I2C
- Timers: 2 x 8-bit, 1 x 16-bit



# Memory system

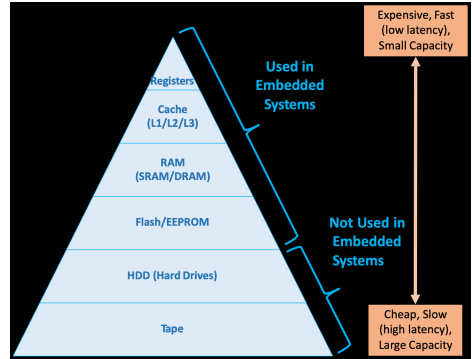
# Review: MCU memory

- Bit
  - Building Block of Memory.
  - Stores 1 piece of Boolean information (0 or 1)
- Byte – 8 Bits. Usually minimum unit for access
- Embedded systems usually have a few kilobytes of memory.
- Memory is one of the limiting factors in embedded systems



# Review: MCU memory

- Computer Systems contain a mixture of memories
- Memory considerations Technology:
  - Capacity
  - Power
  - Speed/Latency
  - Price

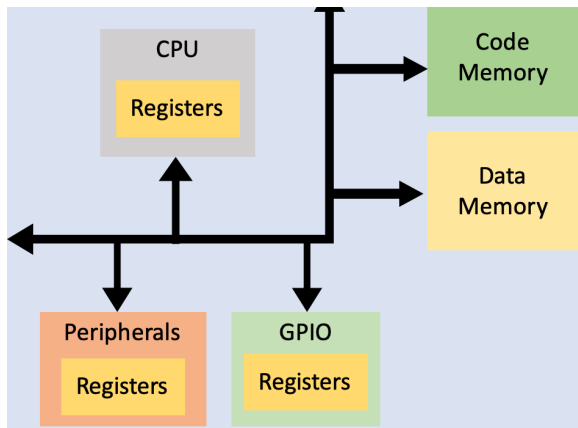


**FIG 10. Memory hierarchy**

The memory hierarchy separates computer storage into a hierarchy based on response time. Fast memory is usually small and expensive. Embedded systems are usually limited to small memory

# Review: MCU memory

- An executable program consists of program code and program data compiled for a particular architecture and platform
- Three types of storage needed for a program
  - Code Memory
  - Data Memory
  - Runtime State of Program
- The compiler tracks and maps memory from program code and program data into segments
  - Code Segment (Flash)
  - Data Segment (SRAM)

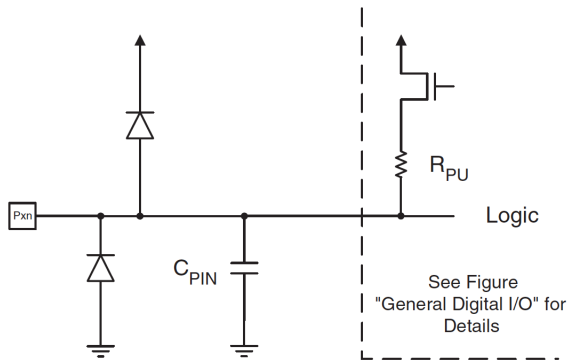




# AVR IO port

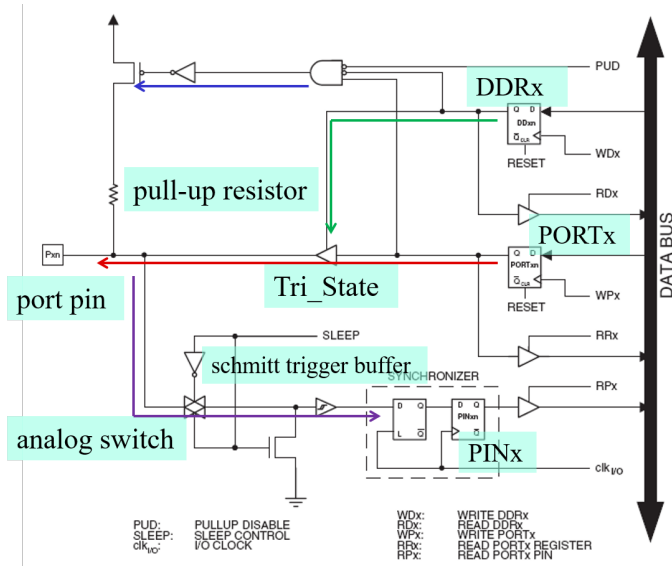
# AVR input/output (I/O) port

- Read-Modify-Write capability, i.e., you can change pin direction, pin value, or pin pull-up resistor without effecting any other pins in the port
- All AVR ports have:
  - bit-selectable pull-up resistors
  - bit-selectable tri-state outputs
  - schmitt trigger (i.e., comparator circuit) input buffers
  - are synchronized to the system clock to prevent metastability
  - have symmetrical DC drive capability



**FIG 11. AVR I/O Pin Equivalent Schematic**

The AVR I/O ports are the path to the outside world. The ports has protection diodes and programmable pull-up resistor



**FIG 12.** The ports are bi-directional I/O ports with optional internal pull-ups.

**TAB 1.** Absolute Maximum Ratings

Operating Temperature .....	-55°C to +125°C
Storage Temperature .....	-65°C to +150°C
Voltage on any Pin except $\overline{\text{RESET}}$ with respect to Ground .....	-0.5V to $V_{CC}+0.5V$
Voltage on $\overline{\text{RESET}}$ with respect to Ground.....	-0.5V to +13.0V
Maximum Operating Voltage .....	6.0V
DC Current per I/O Pin .....	40.0 mA
DC Current $V_{CC}$ and GND Pins.....	200.0 - 400.0mA

## TAB 2. AVR I/O port DC characteristics

$T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 2.7\text{V}$  to  $5.5\text{V}$  (unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Units
$V_{IL}$	Input Low Voltage except XTAL1 and RESET pins	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	-0.5		$0.2 V_{CC}^{(1)}$	V
$V_{IH}$	Input High Voltage except XTAL1 and RESET pins	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	$0.6 V_{CC}^{(2)}$		$V_{CC} + 0.5$	
$V_{IL1}$	Input Low Voltage XTAL1 pin	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	-0.5		$0.1 V_{CC}^{(1)}$	
$V_{IH1}$	Input High Voltage XTAL1 pin	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	$0.7 V_{CC}^{(2)}$		$V_{CC} + 0.5$	
$V_{IL2}$	Input Low Voltage RESET pin	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	-0.5		$0.2 V_{CC}^{(1)}$	
$V_{IH2}$	Input High Voltage RESET pin	$V_{CC} = 2.7\text{V} - 5.5\text{V}$	$0.85 V_{CC}^{(2)}$		$V_{CC} + 0.5$	
$V_{OL}$	Output Low Voltage <sup>(3)</sup> (Ports A,B,C,D, E, F, G)	$I_{OL} = 20\text{mA}$ , $V_{CC} = 5\text{V}$ $I_{OL} = 10\text{mA}$ , $V_{CC} = 3\text{V}$			0.7	V
					0.5	V
$V_{OH}$	Output High Voltage <sup>(4)</sup> (Ports A,B,C,D, E, F, G)	$I_{OH} = -20\text{mA}$ , $V_{CC} = 5\text{V}$ $I_{OH} = -10\text{mA}$ , $V_{CC} = 3\text{V}$	4.2			V
			2.2			V
$I_{IL}$	Input Leakage Current I/O Pin	$V_{CC} = 5.5\text{V}$ , pin low (absolute value)			1.0	$\mu\text{A}$
$I_{IH}$	Input Leakage Current I/O Pin	$V_{CC} = 5.5\text{V}$ , pin high (absolute value)			1.0	
$R_{RST}$	Reset Pull-up Resistor		30		85	$\text{k}\Omega$
$R_{PEN}$	PEN Pull-up Resistor		30		60	
$R_{PU}$	I/O Pin Pull-up Resistor		20		50	

## TAB 3. AVR I/O port DC characteristics (continued)

$T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 2.7\text{V}$  to  $5.5\text{V}$  (unless otherwise noted) (Continued)

Symbol	Parameter	Condition	Min	Typ	Max	Units
$I_{CC}$	Power Supply Current	Active 4MHz, $V_{CC} = 3\text{V}$ (ATmega128L)		5	5.5	mA
		Active 8MHz, $V_{CC} = 5\text{V}$ (ATmega128)		17	19	
		Idle 4MHz, $V_{CC} = 3\text{V}$ (ATmega128L)		2	2.5	
		Idle 8MHz, $V_{CC} = 5\text{V}$ (ATmega128)		8	11	
	Power-down mode	WDT enabled, $V_{CC} = 3\text{V}$		< 15	25	$\mu\text{A}$
		WDT disabled, $V_{CC} = 3\text{V}$		< 5	10	
$V_{ACIO}$	Analog Comparator Input Offset Voltage	$V_{CC} = 5\text{V}$ $V_{in} = V_{CC}/2$			40	mV
$I_{ACLK}$	Analog Comparator Input Leakage Current	$V_{CC} = 5\text{V}$ $V_{in} = V_{CC}/2$	-50		50	nA
$t_{ACPD}$	Analog Comparator Propagation Delay	$V_{CC} = 2.7\text{V}$ $V_{CC} = 5.0\text{V}$		750 500		ns

- Notes:
- "Max" means the highest value where the pin is guaranteed to be read as low
  - "Min" means the lowest value where the pin is guaranteed to be read as high
  - Although each I/O port can sink more than the test conditions (20mA at  $V_{CC} = 5\text{V}$ , 10mA at  $V_{CC} = 3\text{V}$ ) under steady state conditions (non-transient), the following must be observed:  
TQFP and QFN/MLF Package:
    - The sum of all IOL, for all ports, should not exceed 400mA.
    - The sum of all IOL, for ports A0 - A7, G2, C3 - C7 should not exceed 100mA.
    - The sum of all IOL, for ports C0 - C2, G0 - G1, D0 - D7, XTAL2 should not exceed 100mA.
    - The sum of all IOL, for ports B0 - B7, G3 - G4, E0 - E7 should not exceed 100mA.
    - The sum of all IOL, for ports F0 - F7, should not exceed 100mA.
 If IOL exceeds the test condition, VOL may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test condition.
  - Although each I/O port can source more than the test conditions (20mA at  $V_{CC} = 5\text{V}$ , 10mA at  $V_{CC} = 3\text{V}$ ) under steady state conditions (non-transient), the following must be observed:  
TQFP and QFN/MLF Package:
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# AVR MCU connection to a PCB

# How to you connect the MCU to a circuit?

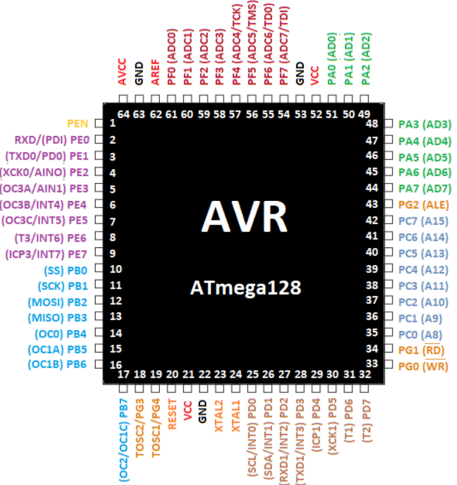


FIG 13. ATMEGA128 pin out

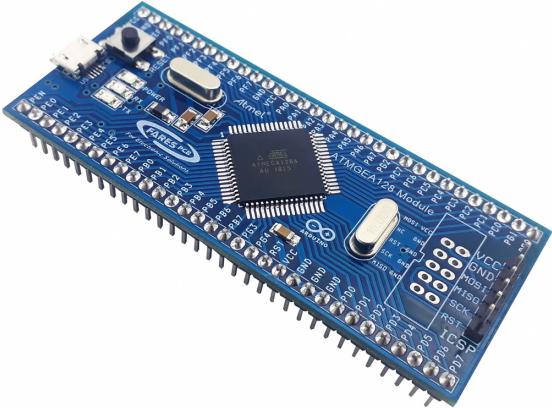
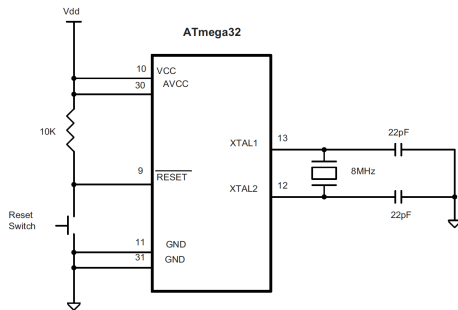


FIG 14. ATMEGA128 Module with Arduino bootloader

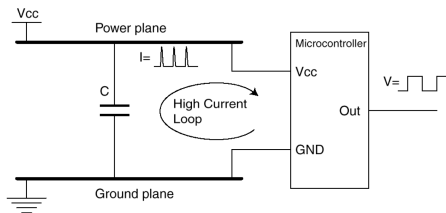


# AVR pins connection

- **VCC**—this pin provides supply voltage to the chip. The typical voltage source is +5 V. Some AVR family members have lower voltage for VCC pins in order to reduce the noise and power dissipation of the AVR system.
- **AVCC** is the supply voltage pin for Port A and the A/D Converter. It should be externally connected to VCC, even if the ADC is not used.
- **AREF** is the analog reference pin for ADC.



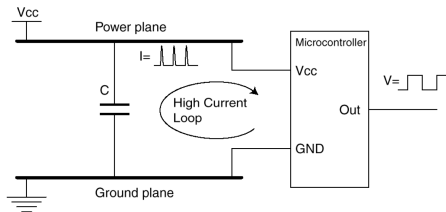
# Digital power supply



## FIG 15. Insufficient power supply decoupling

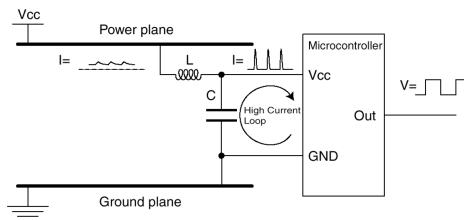
The capacitor is placed too far away from the microcontroller, creating a large high current loop. As a result of this, noise is spread more easily to other devices on the board, and radiated emission from the board is increased even further. The whole ground plane will act as an antenna for the noise, instead of only the high current loop.

# Digital power supply



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**FIG 16. Better placement of the capacitor**

The lines that are part of the high current loop are not part of the power or ground planes. This prevents the power and ground planes to spread a lot of noise. Furthermore, a series inductor is inserted to reduce the switching noise on the power plane.

# Analog power supply

- The ADC has a separate analog supply voltage pin called AVCC.
- AVCC make sure that the analog circuits less prone to the digital noise originating from the switching of the digital circuits.
- The ADC supply voltage must be decoupled separately
- The analog ground should be separated from the digital ground.

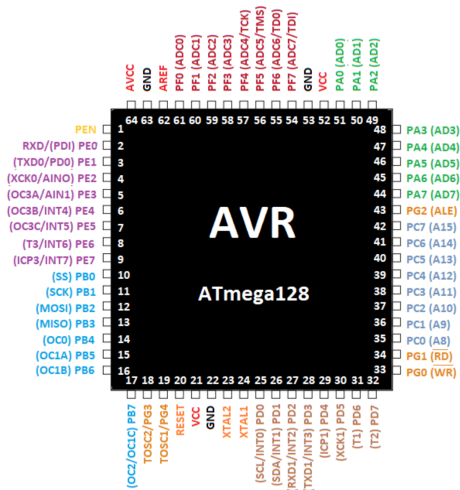
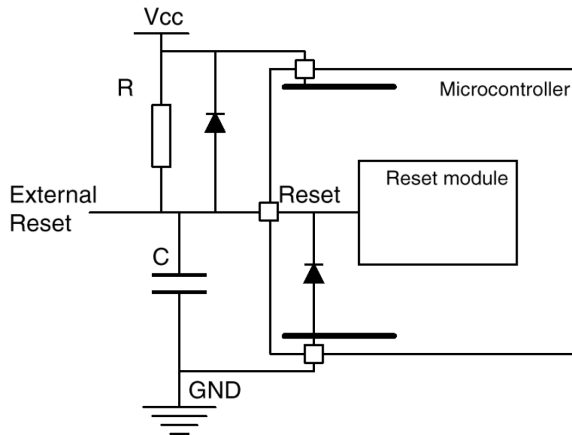


FIG 17. ATMEGA128 pin out

# Reset hardware

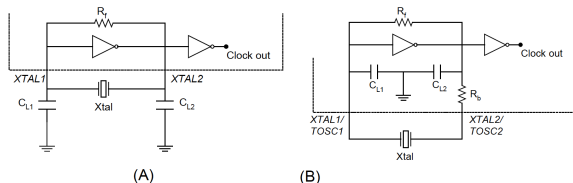
- The RESET pin on the AVR is active LOW, and setting the pin LOW externally will thus result in a reset of the AVR.
- The recommended pull-up resistor is 4.7kOhm or larger
- The capacitor protect the RESET line further from noise
- The components should be located physically close to the RESET pin of the AVR.



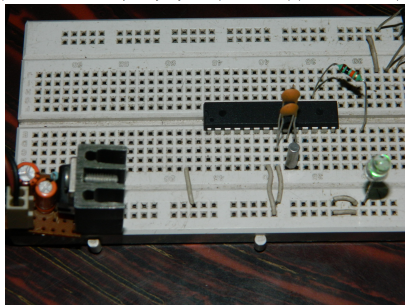
**FIG 18.** Recommended Reset Pin connection.

# Oscillator Hardware

- The oscillator circuit is the “heartbeat” of the system and is crucial to correct operation.
- As a general rule, the speed at which an embedded system runs is directly determined by the oscillator frequency: in most cases, if you double the oscillator frequency, the application will run twice as fast.
- Although most MCU have internal oscillator, it is often necessary to use an external oscillator for an accurate and stable frequency



- Notes: (A) Oscillator circuit for crystals and ceramic resonators faster than 400kHz  
(B) Circuit for low frequency crystals (32.768kHz) (not on all AVRs)



**The end**